

May 2001

# FQP13N06L

## **60V LOGIC N-Channel MOSFET**

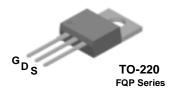
## **General Description**

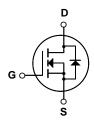
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/ DC converters, and high efficiency switching for power management in portable and battery operated products.

#### **Features**

- 13.6A, 60V,  $R_{DS(on)}$  = 0.11 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 4.8 nC)
- Low Crss (typical 17 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP13N06L	Units
V <sub>DSS</sub>	Drain-Source Voltage		60	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	°C)	13.6	Α
	- Continuous (T <sub>C</sub> = 100°C)		9.6	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	54.4	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	90	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	13.6	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		45	W
	- Derate above 25°C		0.3	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

# **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.35	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
$\Delta BV_{DSS}$ / $\Delta T_J$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.05		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 48 V, T <sub>C</sub> = 150°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics			,		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.5	V
R <sub>DS(on)</sub>	Static Drain-Source	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.8 A		0.088	0.11	
' DS(on)	On-Resistance	V <sub>GS</sub> =5 V, I <sub>D</sub> =6.8 A		0.110		Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 6.8 A (Note 4)		7		S
Dynami	ic Characteristics					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		270	350	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		95	125	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1		17	23	pF
Switchi	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V 20 V I 6 8 A		8	25	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 6.8 \text{ A},$		90	190	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 25 \Omega$		20	50	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		40	90	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 48 V, I <sub>D</sub> = 13.6 A,		4.8	6.4	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = 5 \text{ V}$		1.6		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		2.7		nC
	Source Diode Characteristics a				42.0	
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				13.6	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F				54.4	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 13.6 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 13.6 \text{ A,}$		45		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		45		nC

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L =  $570\mu$ H, I $_{AS}$  = 13.6A, V $_{DD}$  = 25V, R $_{G}$  =  $25~\Omega$ , Starting T $_{J}$  =  $25^{\circ}$ C 3. I $_{SD}$   $\leq 13.6A$ , di/dt  $\leq 300$ A/ $\mu$ s, V $_{DD}$   $\leq BV_{DSS}$ , Starting T $_{J}$  =  $25^{\circ}$ C 4. Pulse Test : Pulse width  $\leq 300\mu$ s, Duty cycle  $\leq 2\%$  5. Essentially independent of operating temperature

# **Typical Characteristics**

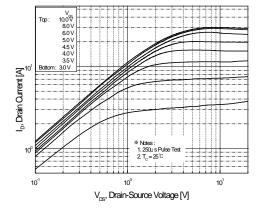


Figure 1. On-Region Characteristics

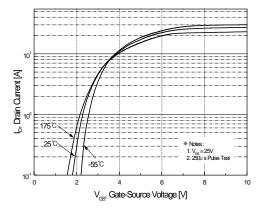


Figure 2. Transfer Characteristics

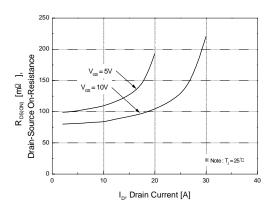


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

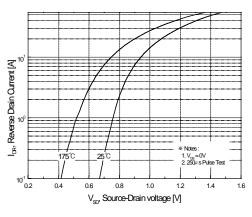


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

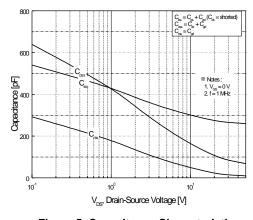


Figure 5. Capacitance Characteristics

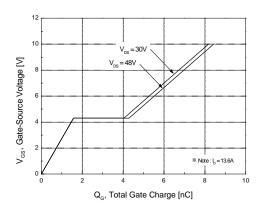
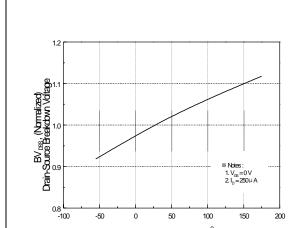


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

T,, Junction Temperature [°C]

150

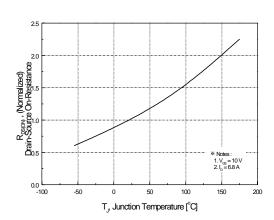


Figure 8. On-Resistance Variation vs. Temperature

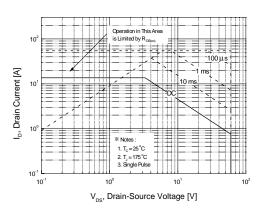


Figure 9. Maximum Safe Operating Area

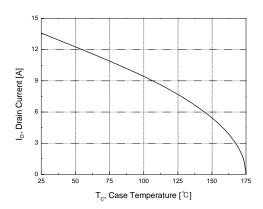


Figure 10. Maximum Drain Current vs. Case Temperature

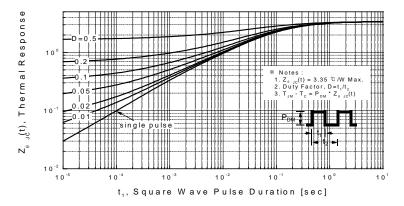
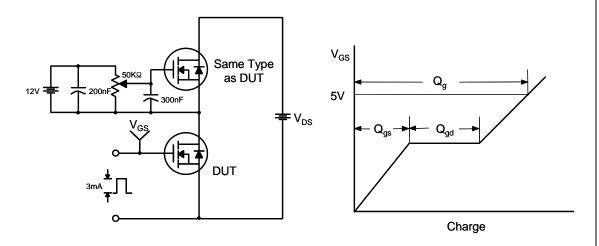


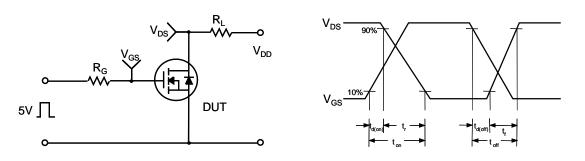
Figure 11. Transient Thermal Response Curve

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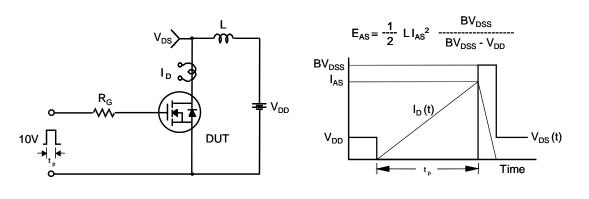
# **Gate Charge Test Circuit & Waveform**



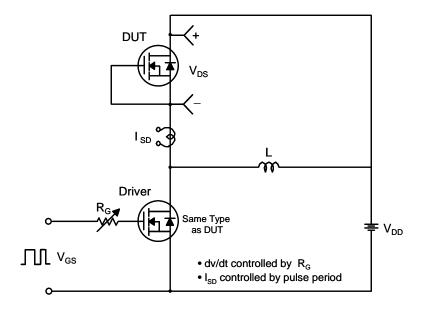
## **Resistive Switching Test Circuit & Waveforms**

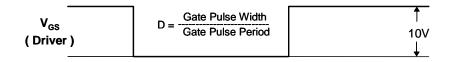


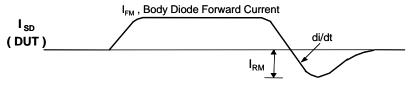
# **Unclamped Inductive Switching Test Circuit & Waveforms**



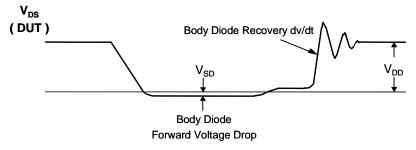
### Peak Diode Recovery dv/dt Test Circuit & Waveforms

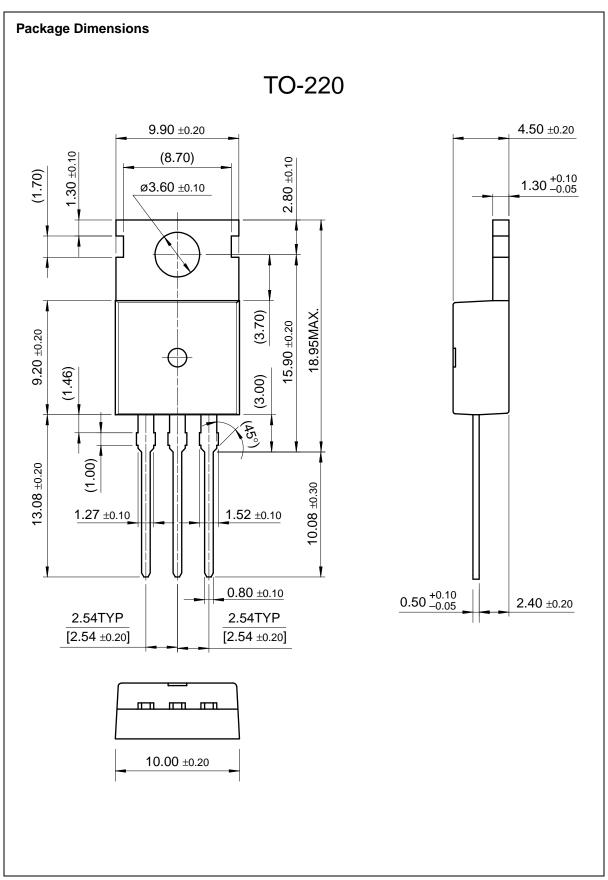






Body Diode Reverse Current





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